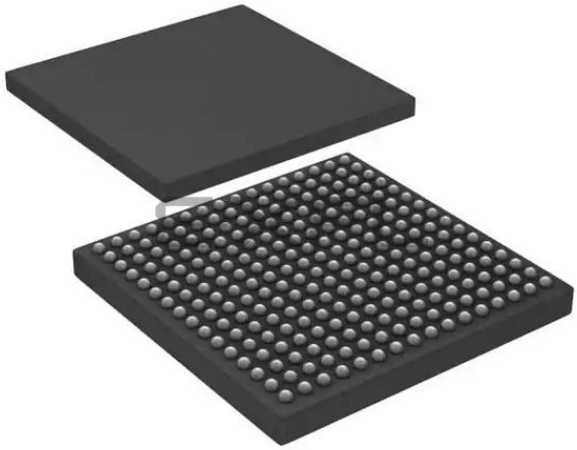

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	180MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, IrDA, Microwire, QEI, SD, SPI, SSI, SSP, UART/USART, USB, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, LCD, Motor Control PWM, POR, PWM, WDT
Number of I/O	164
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	16K x 8
RAM Size	136K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 8x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	256-LBGA
Supplier Device Package	256-LBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc1857fet256-551

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
P1_5	R5	J4	48	65	[2]	N; PU	I/O	**GPIO1[8] —** General purpose digital input/output pin.
							O	**CTOUT_10 —** SCTimer/PWM output 10. Match output 3 of timer 3.
							-	**R —** Function reserved.
							O	**EMC_CS0 —** LOW active Chip Select 0 signal.
							I	**USB0_PWR_FAULT —** Port power fault signal indicating overcurrent condition; this signal monitors over-current on the USB bus (external circuitry required to detect over-current condition).
							I/O	**SSP1_SSEL —** Slave Select for SSP1.
							-	**R —** Function reserved.
							O	**SD_POW —** SD/MMC card power monitor output.
P1_6	T4	K4	49	67	[2]	N; PU	I/O	**GPIO1[9] —** General purpose digital input/output pin.
							I	**CTIN_5 —** SCTimer/PWM input 5. Capture input 2 of timer 2.
							-	**R —** Function reserved.
							O	**EMC_WE —** LOW active Write Enable signal.
							-	**R —** Function reserved.
							O	**EMC_BLS0 —** LOW active Byte Lane select signal 0.
							-	**R —** Function reserved.
							I/O	**SD_CMD —** SD/MMC command signal.
P1_7	T5	G4	50	69	[2]	N; PU	I/O	**GPIO1[0] —** General purpose digital input/output pin.
							I	**U1_DSR —** Data Set Ready input for UART1.
							O	**CTOUT_13 —** SCTimer/PWM output 13. Match output 3 of timer 3.
							I/O	**EMC_D0 —** External memory data line 0.
							O	**USB0_PPWR —** VBUS drive signal (towards external charge pump or power management unit); indicates that VBUS must be driven (active HIGH). Add a pull-down resistor to disable the power switch at reset. This signal has opposite polarity compared to the USB_PPWR used on other NXP LPC parts.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

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Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
P1_12	R9	K7	56	78	[2]	N; PU	I/O	**GPIO1[5] —** General purpose digital input/output pin.
							I	**U1_DCD —** Data Carrier Detect input for UART1.
							-	**R —** Function reserved.
							I/O	**EMC_D5 —** External memory data line 5.
							I	**T0_CAP1 —** Capture input 1 of timer 0.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SD_DAT3 —** SD/MMC data bus line 3.
P1_13	R10	H8	60	83	[2]	N; PU	I/O	**GPIO1[6] —** General purpose digital input/output pin.
							O	**U1_TXD —** Transmitter output for UART1.
							-	**R —** Function reserved.
							I/O	**EMC_D6 —** External memory data line 6.
							I	**T0_CAP0 —** Capture input 0 of timer 0.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**SD_CD —** SD/MMC card detect input.
P1_14	R11	J8	61	85	[2]	N; PU	I/O	**GPIO1[7] —** General purpose digital input/output pin.
							I	**U1_RXD —** Receiver input for UART1.
							-	**R —** Function reserved.
							I/O	**EMC_D7 —** External memory data line 7.
							O	**T0_MAT2 —** Match output 2 of timer 0.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P1_15	T12	K8	62	87	[2]	N; PU	I/O	**GPIO0[2] —** General purpose digital input/output pin.
							O	**U2_TXD —** Transmitter output for USART2.
							-	**R —** Function reserved.
							I	**ENET_RXD0 —** Ethernet receive data 0 (RMII/MII interface).
							O	**T0_MAT1 —** Match output 1 of timer 0.
							-	**R —** Function reserved.
							I/O	**EMC_D8 —** External memory data line 8.
							-	**R —** Function reserved.

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Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
P2_8	J16	C6	98	140	[2]	N; PU	-	**R —** Function reserved. External boot pin (see Table 5)
							O	**CTOUT_0 —** SCTimer/PWM output 0. Match output 0 of timer 0.
							I/O	**U3_DIR —** RS-485/EIA-485 output enable/direction control for USART3.
							I/O	**EMC_A8 —** External memory address line 8.
							I/O	**GPIO5[7] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P2_9	H16	B10	102	144	[2]	N; PU	I/O	**GPIO1[10] —** General purpose digital input/output pin. External boot pin (see Table 5).
							O	**CTOUT_3 —** SCTimer/PWM output 3. Match output 3 of timer 0.
							I/O	**U3_BAUD —** Baud pin for USART3.
							I/O	**EMC_A0 —** External memory address line 0.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P2_10	G16	E8	104	146	[2]	N; PU	I/O	**GPIO0[14] —** General purpose digital input/output pin.
							O	**CTOUT_2 —** SCTimer/PWM output 2. Match output 2 of timer 0.
							O	**U2_TXD —** Transmitter output for USART2.
							I/O	**EMC_A1 —** External memory address line 1.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P2_11	F16	A9	105	148	[2]	N; PU	I/O	**GPIO1[11] —** General purpose digital input/output pin.
							O	**CTOUT_5 —** SCTimer/PWM output 5. Match output 3 of timer 3.
							I	**U2_RXD —** Receiver input for USART2.
							I/O	**EMC_A2 —** External memory address line 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

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Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
P4_3	C2	-	7	10	[5]	N; PU	I/O	**GPIO2[3] —** General purpose digital input/output pin.
							O	**CTOUT_3 —** SCTimer/PWM output 3. Match output 3 of timer 0.
							O	**LCD_VD2 —** LCD data.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**LCD_VD21 —** LCD data.
							I/O	**U3_BAUD —** Baud pin for USART3.
							-	**R —** Function reserved.
							AI	**ADC0_0 —** ADC0 and ADC1, input channel 0. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.
P4_4	B1	-	9	14	[5]	N; PU	I/O	**GPIO2[4] —** General purpose digital input/output pin.
							O	**CTOUT_2 —** SCTimer/PWM output 2. Match output 2 of timer 0.
							O	**LCD_VD1 —** LCD data.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**LCD_VD20 —** LCD data.
							I/O	**U3_DIR —** RS-485/EIA-485 output enable/direction control for USART3.
							-	**R —** Function reserved.
							AO	**DAC —** DAC output. Configure the pin as GPIO input and use the analog function select register in the SCU to select the DAC.
P4_5	D2	-	10	15	[2]	N; PU	I/O	**GPIO2[5] —** General purpose digital input/output pin.
							O	**CTOUT_5 —** SCTimer/PWM output 5. Match output 3 of timer 3.
							O	**LCD_FP —** Frame pulse (STN). Vertical synchronization pulse (TFT).
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

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Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
P5_7	R12	-	65	91	[2]	N; PU	I/O	**GPIO2[7] —** General purpose digital input/output pin.
							O	**MCOA2 —** Motor control PWM channel 2, output A.
							I/O	**EMC_D11 —** External memory data line 11.
							-	**R —** Function reserved.
							I	**U1_RXD —** Receiver input for UART1.
							O	**T1_MAT3 —** Match output 3 of timer 1.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_0	M12	H7	73	105	[2]	N; PU	-	**R —** Function reserved.
							O	**I2S0_RX_MCLK —** I^2S receive master clock.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**I2S0_RX_SCK —** Receive Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the *I^2S-bus specification*.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_1	R15	G5	74	107	[2]	N; PU	I/O	**GPIO3[0] —** General purpose digital input/output pin.
							O	**$\overline{\text{EMC\_DYCS1}}$ —** SDRAM chip select 1.
							I/O	**U0_UCLK —** Serial clock input/output for USART0 in synchronous mode.
							I/O	**I2S0_RX_WS —** Receive Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the *I^2S-bus specification*.
							-	**R —** Function reserved.
							I	**T2_CAP0 —** Capture input 2 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_2	L13	J9	78	111	[2]	N; PU	I/O	**GPIO3[1] —** General purpose digital input/output pin.
							O	**EMC_CKEOUT1 —** SDRAM clock enable 1.
							I/O	**U0_DIR —** RS-485/EIA-485 output enable/direction control for USART0.
							I/O	**I2S0_RX_SDA —** I^2S Receive data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the *I^2S-bus specification*.
							-	**R —** Function reserved.
							I	**T2_CAP1 —** Capture input 1 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

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Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
P6_7	J13	-	85	123	[2]	N; PU	-	**R —** Function reserved.
							I/O	**EMC_A15 —** External memory address line 15.
							-	**R —** Function reserved.
							O	**USB0_IND1 —** USB0 port indicator LED control output 1.
							I/O	**GPIO5[15] —** General purpose digital input/output pin.
							O	**T2_MAT0 —** Match output 0 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_8	H13	-	86	125	[2]	N; PU	-	**R —** Function reserved.
							I/O	**EMC_A14 —** External memory address line 14.
							-	**R —** Function reserved.
							O	**USB0_IND0 —** USB0 port indicator LED control output 0.
							I/O	**GPIO5[16] —** General purpose digital input/output pin.
							O	**T2_MAT1 —** Match output 1 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_9	J15	F8	97	139	[2]	N; PU	I/O	**GPIO3[5] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**$\overline{\text{EMC\_DYCS0}}$ —** SDRAM chip select 0.
							-	**R —** Function reserved.
							O	**T2_MAT2 —** Match output 2 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_10	H15	-	100	142	[2]	N; PU	I/O	**GPIO3[6] —** General purpose digital input/output pin.
							O	**$\overline{\text{MCABORT}}$ —** Motor control PWM, LOW-active fast abort.
							-	**R —** Function reserved.
							O	**EMC_DQMOUT1 —** Data mask 1 used with SDRAM and static devices.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

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Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
P9_3	M6	-	-	79	[2]	N; PU	I/O	**GPIO4[15] —** General purpose digital input/output pin.
							O	**MCOA0 —** Motor control PWM channel 0, output A.
							O	**USB1_IND1 —** USB1 Port indicator LED control output 1.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**ENET_RXD2 —** Ethernet receive data 2 (MII interface).
							-	**R —** Function reserved.
							O	**U3_TXD —** Transmitter output for USART3.
P9_4	N10	-	-	92	[2]	N; PU	-	**R —** Function reserved.
							O	**MCOB0 —** Motor control PWM channel 0, output B.
							O	**USB1_IND0 —** USB1 Port indicator LED control output 0.
							-	**R —** Function reserved.
							I/O	**GPIO5[17] —** General purpose digital input/output pin.
							O	**ENET_TXD2 —** Ethernet transmit data 2 (MII interface).
							-	**R —** Function reserved.
							I	**U3_RXD —** Receiver input for USART3.
P9_5	M9	-	69	98	[2]	N; PU	-	**R —** Function reserved.
							O	**MCOA1 —** Motor control PWM channel 1, output A.
							O	**USB1_PPWR —** VBUS drive signal (towards external charge pump or power management unit); indicates that VBUS must be driven (active HIGH). Add a pull-down resistor to disable the power switch at reset. This signal has opposite polarity compared to the $\overline{\text{USB\_PPWR}}$ used on other NXP LPC parts.
							-	**R —** Function reserved.
							I/O	**GPIO5[18] —** General purpose digital input/output pin.
							O	**ENET_TXD3 —** Ethernet transmit data 3 (MII interface).
							-	**R —** Function reserved.
							O	**U0_TXD —** Transmitter output for USART0.
P9_6	L11	-	72	103	[2]	N; PU	I/O	**GPIO4[11] —** General purpose digital input/output pin.
							O	**MCOB1 —** Motor control PWM channel 1, output B.
							I	**USB1_PWR_FAULT —** USB1 Port power fault signal indicating over-current condition; this signal monitors over-current on the USB1 bus (external circuitry required to detect over-current condition).
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**ENET_COL —** Ethernet Collision detect (MII interface).
							-	**R —** Function reserved.
							I	**U0_RXD —** Receiver input for USART0.

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Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
PB_3	A13	-	-	178	[2]	N; PU	-	**R —** Function reserved.
							I/O	**USB1_ULPI_D6 —** ULPI link bidirectional data line 6.
							O	**LCD_VD20 —** LCD data.
							-	**R —** Function reserved.
							I/O	**GPIO5[23] —** General purpose digital input/output pin.
							O	**CTOUT_8 —** SCTimer/PWM output 8. Match output 0 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PB_4	B11	-	-	180	[2]	N; PU	-	**R —** Function reserved.
							I/O	**USB1_ULPI_D5 —** ULPI link bidirectional data line 5.
							O	**LCD_VD15 —** LCD data.
							-	**R —** Function reserved.
							I/O	**GPIO5[24] —** General purpose digital input/output pin.
							I	**CTIN_5 —** SCTimer/PWM input 5. Capture input 2 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PB_5	A12	-	-	181	[2]	N; PU	-	**R —** Function reserved.
							I/O	**USB1_ULPI_D4 —** ULPI link bidirectional data line 4.
							O	**LCD_VD14 —** LCD data.
							-	**R —** Function reserved.
							I/O	**GPIO5[25] —** General purpose digital input/output pin.
							I	**CTIN_7 —** SCTimer/PWM input 7.
							O	**LCD_PWR —** LCD panel power enable.
							-	**R —** Function reserved.
PB_6	A6	-	-	-	[5]	N; PU	-	**R —** Function reserved.
							I/O	**USB1_ULPI_D3 —** ULPI link bidirectional data line 3.
							O	**LCD_VD13 —** LCD data.
							-	**R —** Function reserved.
							I/O	**GPIO5[26] —** General purpose digital input/output pin.
							I	**CTIN_6 —** SCTimer/PWM input 6. Capture input 1 of timer 3.
							O	**LCD_VD19 —** LCD data.
							-	**R —** Function reserved.
							AI	**ADC0_6** and ADC1 **—** ADC0, input channel 6. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.

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Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
PD_8	P8	-	-	74	[2]	N; PU	-	**R —** Function reserved.
							I	**CTIN_6 —** SCTimer/PWM input 6. Capture input 1 of timer 3.
							I/O	**EMC_D22 —** External memory data line 22.
							-	**R —** Function reserved.
							I/O	**GPIO6[22] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PD_9	T11	-	-	84	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_13 —** SCTimer/PWM output 13. Match output 3 of timer 3.
							I/O	**EMC_D23 —** External memory data line 23.
							-	**R —** Function reserved.
							I/O	**GPIO6[23] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PD_10	P11	-	-	86	[2]	N; PU	-	**R —** Function reserved.
							I	**CTIN_1 —** SCTimer/PWM input 1. Capture input 1 of timer 0. Capture input 1 of timer 2.
							O	**$\overline{\text{EMC\_BLS3}}$ —** LOW active Byte Lane select signal 3.
							-	**R —** Function reserved.
							I/O	**GPIO6[24] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PD_11	N9	-	-	88	[2]	N; PU	-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**$\overline{\text{EMC\_CS3}}$ —** LOW active Chip Select 3 signal.
							-	**R —** Function reserved.
							I/O	**GPIO6[25] —** General purpose digital input/output pin.
							I/O	**USB1_ULPI_D0 —** ULPI link bidirectional data line 0.
							O	**CTOUT_14 —** SCTimer/PWM output 14. Match output 2 of timer 3.
							-	**R —** Function reserved.

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Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
WAKEUP0	A9	A4	130	187	[11]	I; IA	I	External wake-up input; can raise an interrupt and can cause wake-up from any of the low-power modes. A pulse with a duration of at least 45 ns wakes up the part. Input 0 of the event monitor. No internal pull-up is enabled when this pin is configured as input.
WAKEUP1	A10	-	-	-	[11]	I; IA	I	External wake-up input; can raise an interrupt and can cause wake-up from any of the low-power modes. A pulse with a duration of at least 45 ns wakes up the part. Input 1 of the event monitor. No internal pull-up is enabled when this pin is configured as input.
WAKEUP2	C9	-	-	-	[11]	I; IA	I	External wake-up input; can raise an interrupt and can cause wake-up from any of the low-power modes. A pulse with a duration of at least 45 ns wakes up the part. Input 2 of the event monitor. This pin does not have an internal pull-up.
WAKEUP3	D8	-	-	-	[11]	I; IA	I	External wake-up input; can raise an interrupt and can cause wake-up from any of the low-power modes. A pulse with a duration of at least 45 ns wakes up the part. This pin does not have an internal pull-up.
ADC pins								
ADC0_0/ ADC1_0/DAC	E3	A2	6	8	[8]	AI; IA	I	ADC input channel 0. Shared between 10-bit ADC0/1 and DAC.
ADC0_1/ ADC1_1	C3	A1	2	4	[8]	AI; IA	I	ADC input channel 1. Shared between 10-bit ADC0/1.
ADC0_2/ ADC1_2	A4	B3	143	206	[8]	AI; IA	I	ADC input channel 2. Shared between 10-bit ADC0/1.
ADC0_3/ ADC1_3	B5	A3	139	200	[8]	AI; IA	I	ADC input channel 3. Shared between 10-bit ADC0/1.
ADC0_4/ ADC1_4	C6	-	138	199	[8]	AI; IA	I	ADC input channel 4. Shared between 10-bit ADC0/1.
ADC0_5/ ADC1_5	B3	-	144	208	[8]	AI; IA	I	ADC input channel 5. Shared between 10-bit ADC0/1.
ADC0_6/ ADC1_6	A5	-	142	204	[8]	AI; IA	I	ADC input channel 6. Shared between 10-bit ADC0/1.
ADC0_7/ ADC1_7	C5	-	136	197	[8]	AI; IA	I	ADC input channel 7. Shared between 10-bit ADC0/1.
RTC pins								
RTC_ALARM	A11	C3	129	186	[11]	-	O	RTC controlled output.
RTCX1	A8	A5	125	182	[8]	-	I	Input to the RTC 32 kHz ultra-low power oscillator circuit.
RTCX2	B8	B5	126	183	[8]	-	O	Output from the RTC 32 kHz ultra-low power oscillator circuit.
$\overline{\text{SAMPLE}}$	B9	-	-	-	[11]	O	O	Event monitor sample output.
Crystal oscillator pins								
XTAL1	D1	B1	12	18	[8]	-	I	Input to the oscillator circuit and internal clock generator circuits.

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Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
XTAL2	E1	C1	13	19	[8]	-	O	Output from the oscillator amplifier.
Power and ground pins								
USB0_VDDA3V3_DRIVER	F3	D1	16	24		-	-	Separate analog 3.3 V power supply for driver.
USB0_VDDA3V3	G3	D2	17	25		-	-	USB 3.3 V separate power supply voltage.
USB0_VSSA_TERM	H3	D3	19	27		-	-	Dedicated analog ground for clean reference for termination resistors.
USB0_VSSA_REF	G1	F2	23	31		-	-	Dedicated clean analog ground for generation of reference currents and voltages.
VDDA	B4	B2	137	198		-	-	Analog power supply and ADC reference voltage.
VBAT	B10	C5	127	184		-	-	RTC power supply: 3.3 V on this pin supplies power to the RTC.
VDDREG	F10, F9, L8, L7	E4, E5, F4	94, 131, 59, 25	135, 188, 195, 82, 33			-	Main regulator power supply.
VPP	E8	-	-	-	[12]	-	-	OTP programming voltage.
VDDIO	D7, E12, F7, F8, G10, H10, J6, J7, K7, L9, L10, N7, N13	F10, K5	5, 36, 41, 71, 77, 107, 111, 141	6, 52, 57, 102, 110, 155, 160, 202	[12]	-	-	I/O power supply.

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7.15.7 High-speed USB Host/Device interface with ULPI (USB1)

Remark: USB1 is available on the following parts: LPC185x and LPC183x. USB1 is not available on the LPC182x and LPC181x parts.

The USB1 interface can operate as a full-speed USB host/device interface or can connect to an external ULPI PHY for High-speed operation.

7.15.7.1 Features

- Complies with *Universal Serial Bus specification 2.0*.
- Complies with *Enhanced Host Controller Interface Specification*.
- Supports auto USB 2.0 mode discovery.
- Supports all high-speed USB-compliant peripherals if connected to external ULPI PHY.
- Supports all full-speed USB-compliant peripherals.
- Supports interrupts.
- Supports Start Of Frame (SOF) frame length adjust.
- This module has its own, integrated DMA engine.
- USB interface electrical test software included in ROM USB stack.

7.15.8 LCD controller

Remark: The LCD controller is only available on parts LPC185x. LCD is not available on parts LPC183x, LPC182x, and LPC181x.

The LCD controller provides all of the necessary control signals to interface directly to various color and monochrome LCD panels. Both STN (single and dual panel) and TFT panels can be operated. The display resolution is selectable and can be up to 1024 × 768 pixels. Several color modes are provided, up to a 24-bit true-color non-palettized mode. An on-chip 512 byte color palette allows reducing bus utilization (that is, memory size of the displayed data) while still supporting many colors.

The LCD interface includes its own DMA controller to allow it to operate independently of the CPU and other system functions. A built-in FIFO acts as a buffer for display data, providing flexibility for system timing. Hardware cursor support can further reduce the amount of CPU time required to operate the display.

7.15.8.1 Features

- AHB master interface to access frame buffer.
- Setup and control via a separate AHB slave interface.
- Dual 16-deep programmable 64-bit wide FIFOs for buffering incoming display data.
- Supports single and dual-panel monochrome Super Twisted Nematic (STN) displays with 4-bit or 8-bit interfaces.
- Supports single and dual-panel color STN displays.
- Supports Thin Film Transistor (TFT) color displays.
- Programmable display resolution including, but not limited to: 320 × 200, 320 × 240, 640 × 200, 640 × 240, 640 × 480, 800 × 600, and 1024 × 768.
- Hardware cursor support for single-panel displays.

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The I²S-bus provides a standard communication interface for digital audio applications.

The *I²S-bus specification* defines a 3-wire serial bus using one data line, one clock line, and one word select signal. The basic I²S-bus connection has one master, which is always the master, and one slave. The I²S-bus interface provides a separate transmit and receive channel, each of which can operate as either a master or a slave.

7.16.5.1 Features

- The interface has separate input/output channels each of which can operate in master or slave mode.
- Capable of handling 8-bit, 16-bit, and 32-bit word sizes.
- Mono and stereo audio data supported.
- The sampling frequency can range from 16 kHz to 192 kHz (16, 22.05, 32, 44.1, 48, 96, 192) kHz.
- Support for an audio master clock.
- Configurable word select period in master mode (separately for I²S-bus input and output).
- Two 8-word FIFO data buffers are provided, one for transmit and one for receive.
- Generates interrupt requests when buffer levels cross a programmable boundary.
- Two DMA requests, controlled by programmable buffer levels. The DMA requests are connected to the GPDMA block.
- Controls include reset, stop and mute options separately for I²S-bus input and I²S-bus output.

7.16.6 C_CAN

Remark: The LPC185x/3x/2x/1x contain two C_CAN controllers.

Controller Area Network (CAN) is the definition of a high performance communication protocol for serial data communication. The C_CAN controller is designed to provide a full implementation of the CAN protocol according to the CAN Specification Version 2.0B. The C_CAN controller can build powerful local networks with low-cost multiplex wiring by supporting distributed real-time control with a high level of reliability.

7.16.6.1 Features

- Conforms to protocol version 2.0 parts A and B.
- Supports bit rate of up to 1 Mbit/s.
- Supports 32 Message Objects.
- Each Message Object has its own identifier mask.
- Provides programmable FIFO mode (concatenation of Message Objects).
- Provides maskable interrupts.
- Supports Disabled Automatic Retransmission (DAR) mode for time-triggered CAN applications.
- Provides programmable loop-back mode for self-test operation.

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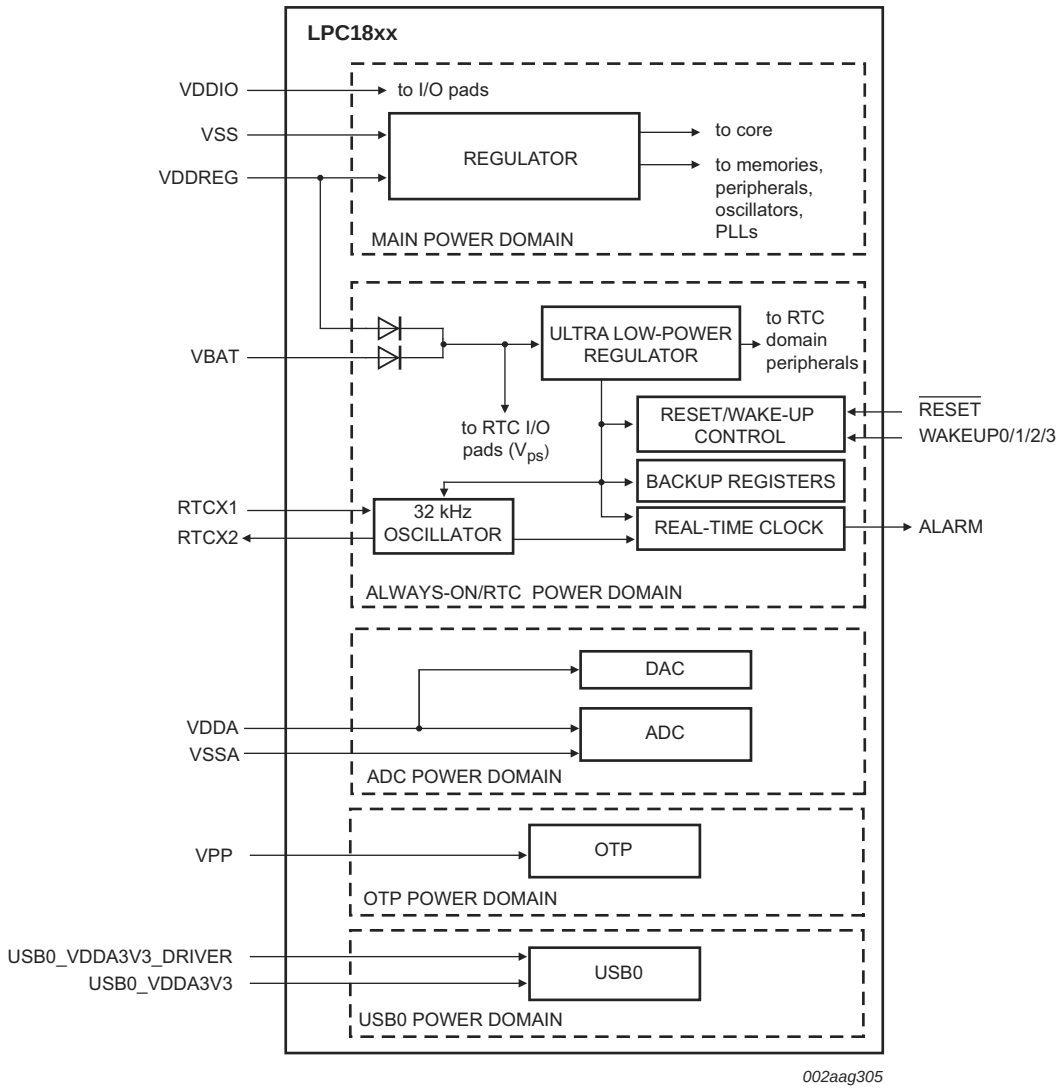

Fig 9. LPC185x/3x/2x/1x Power domains

The LPC185x/3x/2x/1x support four reduced power modes: Sleep, Deep-sleep, Power-down, and Deep power-down.

The LPC185x/3x/2x/1x can wake up from Deep-sleep, Power-down, and Deep power-down modes via the WAKEUP[3:0] pins and interrupts generated by battery powered blocks in the RTC power domain.

7.20.10 Code security (Code Read Protection - CRP)

CRP enables different levels of security so that access to the on-chip flash and use of the JTAG and ISP can be restricted. CRP is invoked by programming a specific pattern into a dedicated flash location. IAP commands are not affected by CRP.

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9. Thermal characteristics

The average chip junction temperature, T_j (°C), can be calculated using the following equation:

$$T_j = T_{amb} + (P_D \times R_{th(j-a)}) \quad (1)$$

- T_{amb} = ambient temperature (°C),
- $R_{th(j-a)}$ = the package junction-to-ambient thermal resistance (°C/W)
- P_D = sum of internal and I/O power dissipation

The internal power dissipation is the product of $I_{DD(REG)(3V3)}$ and $V_{DD(REG)(3V3)}$. The I/O power dissipation of the I/O pins is often small and many times can be negligible. However it can be significant in some applications.

Table 8. Thermal characteristics

Symbol	Parameter	Min	Typ	Max	Unit
$T_{j(max)}$	maximum junction temperature	-	-	125	°C

Table 9. Thermal resistance (LQFP packages)

Symbol	Parameter	Conditions	Thermal resistance in °C/W ±15 %	
			LQFP144	LQFP208
$R_{th(j-a)}$	thermal resistance from junction to ambient	JEDEC (4.5 in × 4 in); still air	38	31
		Single-layer (4.5 in × 3 in); still air	50	39
$R_{th(j-c)}$	thermal resistance from junction to case		11	10

Table 10. Thermal resistance value (BGA packages)

Symbol	Parameter	Conditions	Thermal resistance in °C/W ±15 %	
			LBGA256	TFBGA100
$R_{th(j-a)}$	thermal resistance from junction to ambient	JEDEC (4.5 in × 4 in); still air	29	46
		8-layer (4.5 in × 3 in); still air	24	37
$R_{th(j-c)}$	thermal resistance from junction to case		14	11

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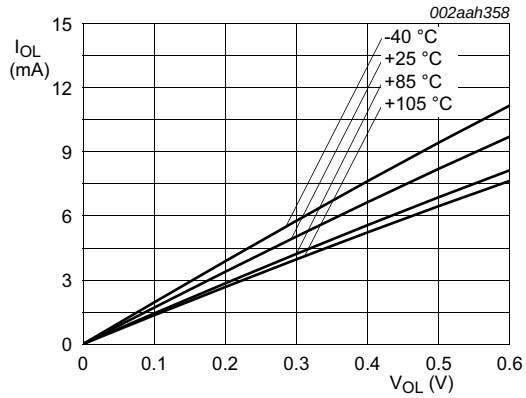
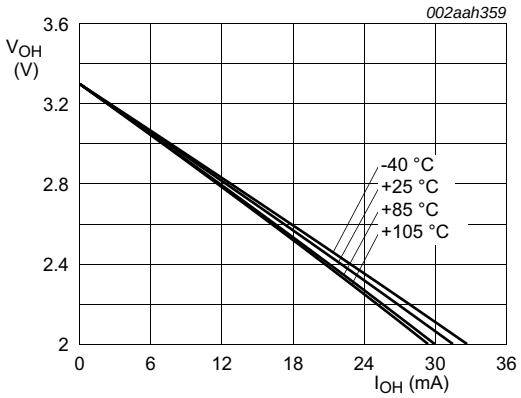
10.3 Electrical pin characteristics



Conditions: $V_{DD(REG)(3V3)} = V_{DD(IO)} = 3.3$ V.

Fig 19. Standard I/O pins; typical LOW level output current I_{OL} versus LOW level output voltage V_{OL}



Conditions: $V_{DD(REG)(3V3)} = V_{DD(IO)} = 3.3$ V.

Fig 20. Standard I/O pins; typical HIGH level output voltage V_{OL} versus HIGH level output current I_{OH}

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10.4 BOD and band gap static characteristics

Table 13. BOD static characteristics[1]

T_{amb} = 25 °C; simulated values for nominal processing.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{th}	threshold voltage	interrupt level 2					
		assertion		-	2.95	-	V
		de-assertion		-	3.03	-	V
		interrupt level 3					
		assertion		-	3.05	-	V
		de-assertion		-	3.13	-	V
		reset level 2					
		assertion		-	2.1	-	V
		de-assertion		-	2.18	-	V
		reset level 3					
		assertion		-	2.2	-	V
		de-assertion		-	2.28	-	V

[1] Interrupt and reset levels are selected by writing to the BODLV1/2 bits in the control register CREGE0, see the *LPC18xx user manual*.

Table 14. Band gap characteristics

$V_{DDA(3V3)}$ over specified ranges; T_{amb} = −40 °C to +105 °C; unless otherwise specified

Symbol	Parameter		Min	Typ	Max	Unit
$V_{ref(bg)}$	band gap reference voltage	[1]	0.707	0.745	0.783	mV

[1] Based on characterization, not tested in production.

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11.2 Wake-up times

Table 17. Dynamic characteristic: Wake-up from Deep-sleep, Power-down, and Deep power-down modes

T_{amb} = −40 °C to +105 °C

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
t_{wake}	wake-up time	from Sleep mode	[2]	$3 \times T_{cy(clk)}$	$5 \times T_{cy(clk)}$	-	ns
		from Deep-sleep and Power-down mode		12	51	-	µs
		from Deep power-down mode		-	200	-	µs
		after reset		-	200	-	µs

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

[2] $T_{cy(clk)}$ = 1/CCLK with CCLK = CPU clock frequency.

11.3 External clock for oscillator in slave mode

Remark: The input voltage on the XTAL1/2 pins must be ≤ 1.2 V (see Table 11). For connecting the oscillator to the XTAL pins, also see Section 13.2 and Section 13.4.

Table 18. Dynamic characteristic: external clock

T_{amb} = −40 °C to +105 °C; $V_{DD(IO)}$ over specified ranges.[1]

Symbol	Parameter	Conditions		Min	Max	Unit
f_{osc}	oscillator frequency			1	25	MHz
$T_{cy(clk)}$	clock cycle time			40	1000	ns
t_{CHCX}	clock HIGH time			$T_{cy(clk)} \times 0.4$	$T_{cy(clk)} \times 0.6$	ns
t_{CLCX}	clock LOW time			$T_{cy(clk)} \times 0.4$	$T_{cy(clk)} \times 0.6$	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

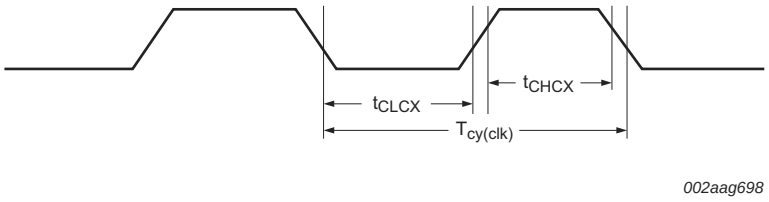

Fig 25. External clock timing (with an amplitude of at least $V_{i(RMS)}$ = 200 mV)

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11.12 SSP interface

Table 27. Dynamic characteristics: SSP pins in SPI mode

T_{amb} = −40 °C to +105 °C; 2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V; C_L = 20 pF; sampled at 10 % and 90 % of the signal level; EHS = 1 for all pins. Simulated values.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
SSP master							
$T_{cy(clk)}$	clock cycle time	full-duplex mode	[1]	$1/(25.5 \times 10^6)$	-	-	s
		when only transmitting		$1/(51 \times 10^6)$	-	-	s
t_{DS}	data set-up time	in SPI mode		12.2	-	-	ns
t_{DH}	data hold time	in SPI mode		−3.6	-	-	ns
$t_{v(Q)}$	data output valid time	in SPI mode		-	-	6.7	ns
$t_{h(Q)}$	data output hold time	in SPI mode		−1.7	-	-	ns
t_{lead}	lead time	continuous transfer mode SPI mode; CPOL = 0; CPHA = 0		$T_{cy(clk)}$ + 3.3	-	$T_{cy(clk)}$ + 8.2	ns
		SPI mode; CPOL = 0; CPHA = 1		$0.5 \times T_{cy(clk)}$ + 3.3	-	$0.5 \times T_{cy(clk)}$ + 8.2	ns
		SPI mode; CPOL = 1; CPHA = 0		$T_{cy(clk)}$ + 3.3	-	$T_{cy(clk)}$ + 8.2	ns
		SPI mode; CPOL = 1; CPHA = 1		$0.5 \times T_{cy(clk)}$ + 3.3	-	$0.5 \times T_{cy(clk)}$ + 8.2	ns
		synchronous serial frame mode		$0.5 \times T_{cy(clk)}$ + 3.3	-	$0.5 \times T_{cy(clk)}$ + 8.2	ns
		microwire frame format		$T_{cy(clk)}$ + 3.3	-	$T_{cy(clk)}$ + 8.2	ns
t_{lag}	lag time	continuous transfer mode SPI mode; CPOL = 0; CPHA = 0		$0.5 \times T_{cy(clk)}$	-	-	ns
		SPI mode; CPOL = 0; CPHA = 1		$T_{cy(clk)}$	-	-	ns
		SPI mode; CPOL = 1; CPHA = 0		$0.5 \times T_{cy(clk)}$	-	-	ns
		SPI mode; CPOL = 1; CPHA = 1		$T_{cy(clk)}$	-	-	ns
		synchronous serial frame mode		$T_{cy(clk)}$	-	-	ns
		microwire frame format		$0.5 \times T_{cy(clk)}$	-	-	ns

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